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In the Claims:

1. (Currently amended) An aqueous composition useful for polishing and removing copper on a semiconductor wafer comprising by weight percent up to 25 oxidizer, 0.05 to 1 inhibitor for a nonferrous metal, 0.01 to 5 complexing agent for the nonferrous metal, 0.01 to 5 modified cellulose, the carboxy methyl cellulose having a degree of substitution of 0.1 to 3.0 and a molecular weight of 20K to 1000K, and balance water at a pH of 2 to 5, wherein said composition is abrasive free and free of polyacrylic acids.
2. (Original) The composition of claim 1 wherein the modified cellulose is water soluble cellulose modified with carboxylic acid functionality from the group consisting of carboxy methyl cellulose, agar gum, arabic gum, ghatti gum, karaya gum, guar gum, pectin, locust bean gum, tragacanth gums, tamarind gum, carrageenan gum, and xantham gum, modified starch, alginic acid, mannuronic acid, guluronic acid, and their modifications, copolymers, and mixtures.
3. (Original) The composition of claim 2 wherein the modified cellulose is carboxy methyl cellulose.
4. (Currently amended) The composition of claim 3 wherein said the carboxy methyl cellulose has a degree of substitution of 0.1 to 3.0 0.7 to 1.2 and a molecular weight of 20K to 1000K 40K to 250K.

5 to 10 Cancelled.